

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A front end module for processing transmission signals and reception signals in each of a first frequency band and a second frequency band, the front end module comprising:

a first separating means for separating the first and second frequency bands from each other, where the first separating means is connected to an antenna;

a second separating means for separating the transmission signals and the reception signals in the first frequency band from each other, where the second separating means is connected to the first separating means and includes a first pair of two acoustic wave elements each of which functions as a filter;

a third separating means for separating the transmission signals and the reception signals in the second frequency band from each other, where the third separating means is connected to the first separating means and includes a second pair of two acoustic wave elements each of which functions as a filter, wherein each of the acoustic wave elements in the first and second pairs of two acoustic wave elements is one of a surface acoustic wave element and a bulk acoustic wave element; and

a single multi-layer substrate that integrates the first to third separating means, wherein

the first separating means is made up of a conductor layer located inside or on a surface of the multi-layer substrate.

2. (Previously Presented) The front end module according to claim 1, wherein: the first pair of acoustic wave elements and the second pair of acoustic wave elements are mounted on the multi-layer substrate; and

at least a part of circuit portions of the second and third separating means except for the pairs of acoustic wave elements is made up of the conductor layer located inside or on the surface of the multi-layer substrate.

3. (Previously Presented) The front end module according to claim 1, wherein the first separating means comprises:

a first filter that allows signals of frequencies in the first frequency band to pass through the first filter and intercepts signals of frequencies in the second frequency band; and

a second filter that allows signals of frequencies in the second frequency band to pass through the second filter and intercepts signals of frequencies in the first frequency band.

4. (Original) The front end module according to claim 1, wherein the transmission signals and the reception signals in each of the first and second frequency bands are signals of a code division multiple access system.

5. (Previously Presented) The front end module according to claim 1, wherein:  
the first separating means includes a filter;  
one of the second and third separating means includes a delay line for impedance adjustment that is provided between one of the acoustic wave elements and the first separating means;

the first pair of two acoustic wave elements and the second pair of two acoustic wave elements are mounted on a top surface of the multi-layer substrate; and

the multi-layer substrate includes, as conductor layers located inside the multi-layer substrate, a ground layer, a conductor layer that forms the delay line and that is disposed between the ground layer and the top surface of the multi-layer substrate; and a conductor layer that forms the filter included in the first separating means and that is disposed between the ground layer and a bottom surface of the multi-layer substrate,

the front end module further comprising a terminal disposed on the bottom surface of the multi-layer substrate and connected to the conductor layer that forms the filter included in the first separating means.

6. (Previously Presented) The front end module according to claim 5, further comprising a matching circuit provided between the delay line and the first separating means, wherein the multi-layer substrate further includes, as another conductor layer located inside the multi-layer substrate, a conductor layer that forms the matching circuit and that is disposed between the ground layer and the top surface of the multi-layer substrate.